

NOT OFFICIALLY ENTERED

Attachment "A"

Pending claims

1-6. (Canceled)

7. (Previously presented) A method for making an electrical component assembly, comprising, in sequence, the steps of:

laminating a film on an active surface of an semiconductor chip;

producing holes in the film to expose contact pads on the active surface of the semiconductor chip;

filling the holes with an electrically conductive material;

placing the semiconductor chip on a substrate with the film located between the semiconductor chip and the substrate; and

reflowing the electrically conductive material in order to attach the semiconductor chip to the substrate.

8. (Original) The method of claim 7 further comprising the step of: coating a surface of the film which faces the substrate with a flux adhesive.